

Features

- High Density Cell Design For Low R_{DS(ON)}
- · Voltage Controlled Small Signal Switch
- · Epoxy Meets UL 94 V-0 Flammability Rating
- · Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note1)
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

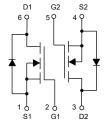
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance:415°C/W Junction to Ambient(Steady-State)^(Note2)

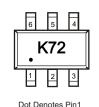
Parameter		Symbol	Rating	Unit	
Drain-Source Voltage	V _{DS}	60	V		
Gate-Source Volltage		V _{GS}	±20	V	
Continuous Drain Current	T _A =25°C		340	mA	
	T _A =100°C	l _D	215		
Pulsed Drain Current ^(Note3)		I _{DM}	1.36	Α	
Total Power Dissipation (Note4)		P _D	300	mW	

Note:

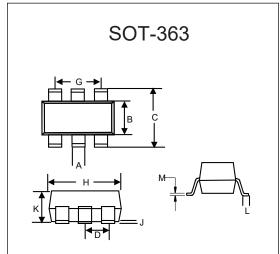
- 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 2. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The Power dissipation P_{DSM} is based on R_{θJA} t≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- 3. Repetitive rating; pulse width limited by max. junction temperature.
- 4. P_{D} is based on max. junction temperature, using junction-ambient thermal resistance.

Internal Structure and Marking Code



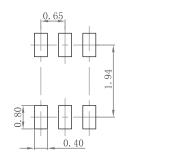


DUAL N-CHANNEL MOSFET



DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	INOTE
Α	0.006	0.014	0.15	0.35	
В	0.045	0.053	1.15	1.35	
С	0.079	0.096	2.00	2.45	
D	0.026		0.65		TYP.
G	0.047	0.055	1.20	1.40	
Н	0.071	0.087	1.80	2.20	
J		0.004		0.10	
K	0.031	0.043	0.80	1.10	
┙	0.010	0.018	0.26	0.46	
М	0.003	0.006	0.08	0.15	

SUGGESTED SOLDER PAD LAYOUT



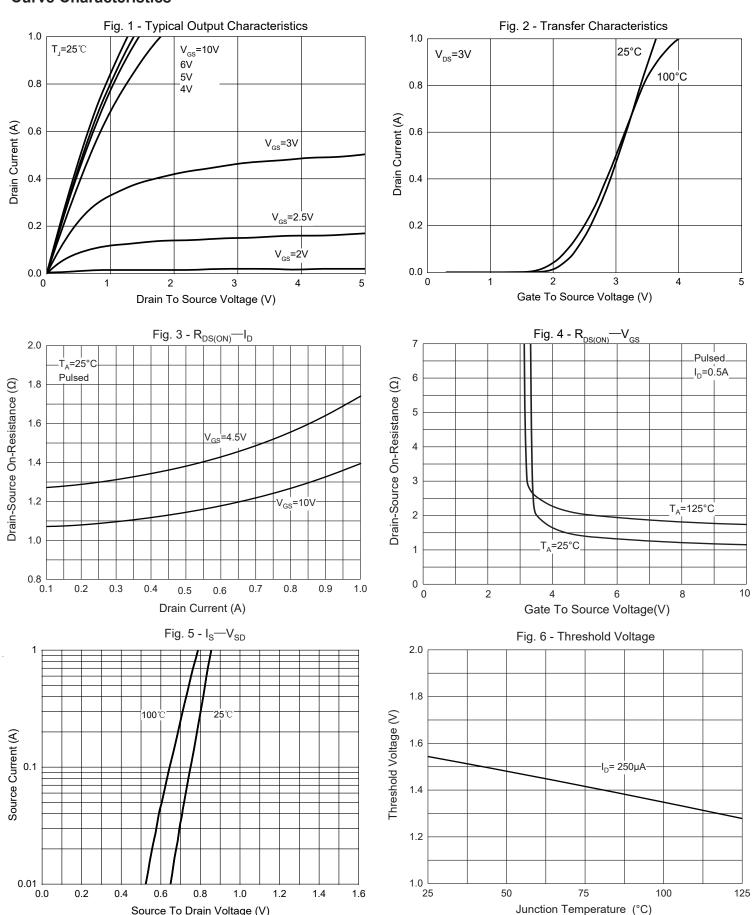


Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static Characteristics	-1		ı	ı	ı	1	
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	60			V	
Gate-Source Leakage Current	I _{GSS} V _{DS} =0V, V _{GS} =±20V				±10	- nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V	0V, V _{GS} =0V		80		
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1.0	1.5	2.5	V	
		V _{GS} =10V, I _D =300mA		1.1	2.5	Ω	
Drain-Source On-Resistance	$R_{DS(on)}$	V _{GS} =4.5V, I _D =200mA		1.3	3		
Forward Transconductance	9 _{fs}	V _{DS} =10V, I _D =200mA	80			ms	
Gate Resistance	R _g	F=1 MHz, Open drain		4.1		Ω	
Diode Characteristics			·				
Continuous Body Diode Current	Is				115	mA	
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =115mA	0.55		1.2	V	
Reverse Recovery Time	t _{rr}	I _F =0.5A, dI _F /dt=100A/μs		9.4		ns	
Reverse Recovery Charge	Q_{rr}	i _F -0.3A, αi _F /αι-100A/μs		3.1		nC	
Dynamic Characteristics							
Input Capacitance	C _{iss}			25.2			
Output Capacitance	C _{oss}	V _{DS} =25V,V _{GS} =0V,f=1MHz		3.5		pF	
Reverse Transfer Capacitance	C _{rss}			2.2			
Total Gate Charge	Qg			1.1			
Gate-Source Charge	Q _{gs}	V _{DS} =25V,V _{GS} =10V,I _D =0.5A		0.19		nC	
Gate-Drain Charge	Q_{gd}			0.25			
Turn-On Delay Time	t _{d(on)}			2.3			
Turn-On Rise Time	t _r	V _{DD} =25V, V _{GEN} =10V,		2.7			
Turn-Off Delay Time	t _{d(off)}	R_{GEN} =25 Ω , I_{DS} =500mA		6.3		ns	
Turn-Off Fall Time	t _f			3			



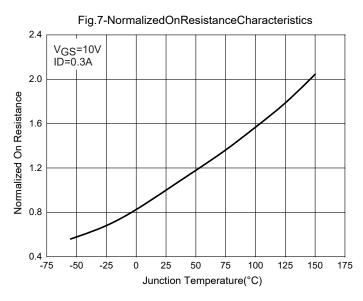
Curve Characteristics

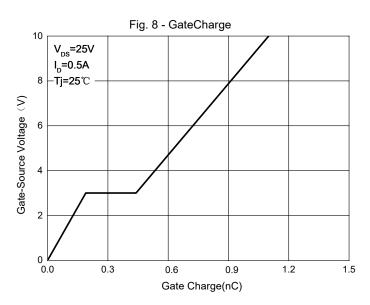


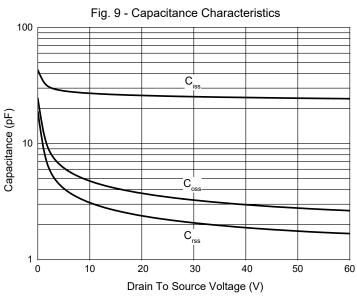
Source To Drain Voltage (V)

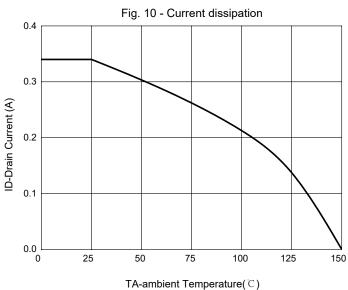


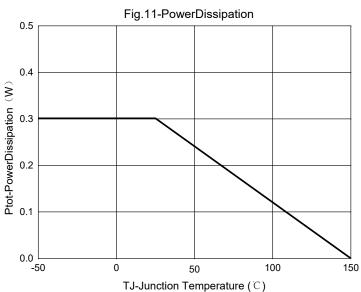
Curve Characteristics





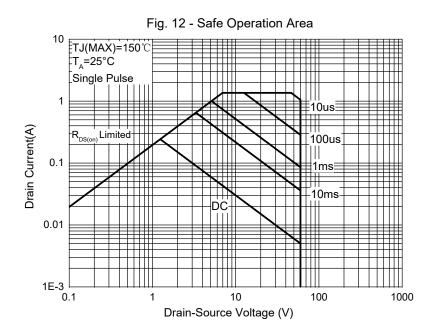


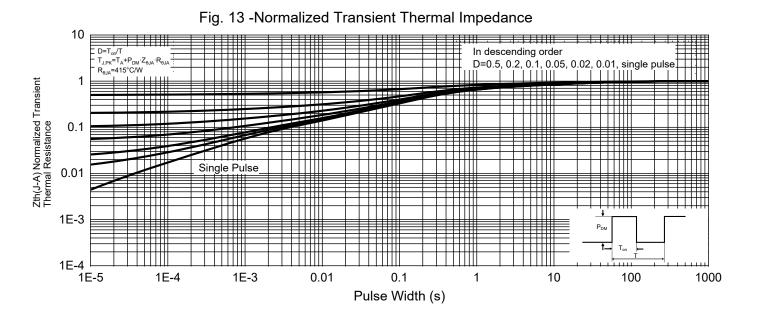






Curve Characteristics







Ordering Information

Device	Packing	
Part Number-TP	Tape&Reel:3Kpcs/Reel	
Part Number-TPQ2	Tape&Reel:3Kpcs/Reel	

For packaging details, go to our website at https://www.mccsemi.com/pdf/ProductPackaging/SOT-363%20Package.pdf

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